

Declaration of Compliance

We declare that our green products for customer comply with all RoHS regulations. We are willing to provide all necessary documentation or information to prove our compliance with the RoHS regulations. It is our responsibility to proactively inform our customer if we identify that there is a potential risk of breaching the RoHS regulations in our product.

1. Product Information:

Model P/N:	Products P/N:
FP5ZZ8632T02A	AS9726-32DB-O-AC-B-TW
FP5ZZ8632T01A	AS9726-32DB-O-AC-F-TW
FP5ZZ8632703A	AS9726-32DB-O-AC-B-CN
FP5ZZ8632702A	AS9726-32DB-O-AC-F-CN
FP5ZZ8632503A	AS9726-32DB-O-AC-B-JP
FP5ZZ8632502A	AS9726-32DB-O-AC-F-JP
FP5ZZ8632403A	AS9726-32DB-O-AC-B-US
FP5ZZ8632402A	AS9726-32DB-O-AC-F-US
FP5ZZ8632303A	AS9726-32DB-O-AC-B-UK
FP5ZZ8632302A	AS9726-32DB-O-AC-F-UK
FP5ZZ8632203A	AS9726-32DB-O-AC-B-EU
FP5ZZ8632202A	AS9726-32DB-O-AC-F-EU
FP5ZZ8632025A	AS9726-32DB-O-AC-B
FP5ZZ8632023A	AS9726-32DB-O-AC-F

Product meets EU RoHS requirements by application of selected exemption(s):

Banned Substance	Threshold Limit	RoHS Exemption*
Lead (Pb)	1,000 ppm (0.1 weight %)	6(c); 7(a); 7(c)-l
Cadmium (Cd)	100 ppm (0.01 weight %)	
Mercury (Hg)	1,000 ppm (0.1 weight %)	
Hexavalent Chromium (Cr ⁶⁺)	1,000 ppm (0.1 weight %)	
Poly Brominated Biphenyls (PBB)	1,000 ppm (0.1 weight %)	
Poly Brominated Diphenyl Ethers (PBDE)	1,000 ppm (0.1 weight %)	
Bis(2-Ethylhexyl) phthalate (DEHP)	1,000 ppm (0.1 weight %)	
Benzyl butyl phthalate (BBP)	1,000 ppm (0.1 weight %)	
Dibutyl phthalate (DBP)	1,000 ppm (0.1 weight %)	
Diisobutyl phthalate (DIBP)	1,000 ppm (0.1 weight %)	

RoHS maximum limit (ppm) does not apply to applications for which exemptions have been granted by the RoHS Directive.

Applicable within the scope of categories and expiry dates as given in Annex III of Directive 2011/65/EU as listed below:

RoHS exemption	RoHS exemption description
6(c)	Copper alloy containing up to 4% lead by weight.
7(a)	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead).
7(c)-l	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

This statement reflects Products listed below that are manufactured by Accton Technology Corporation are in compliance to Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006 concerning the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH). The Candidate List of SVHCs is continually updated at https://echa.europa.eu/candidate-list-table.

This product contains the following REACH Substances of Very High Concern above the limits (0.1% w/w) of component article within REACH:

CAS No.	CAS No. SVHCs in a concentration above 0.1% weight by w				
10124-43-3	Cobalt(II) sulphate				
111-15-9	2-ethoxyethyl acetate				
1303-86-2	Diboron trioxide				
1317-36-8	Lead monoxide (lead oxide)				
12060-00-3	Lead titanium trioxide				
7439-92-1	Lead				
71868-10-5	2-methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one				

Table of toxic and hazardous substances/elements and their content:

(As required by China's management methods for controlling pollution by electronic

产品内含危害物质揭露表	Products	s contain haz	ardous subst	ances expos	ing table		
	危害物质项目 Hazardous Substances Project						
零部件名称 Component Name	铅 (Pb)	镉 (Cd)	汞 (Hg)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯 乙 醚 (PBDE)	
固态硬盘模块 SSD MODULE	X	0	0	0	0	0	
动态随机存取内存模块 DRAM MODULE	Х	0	0	0	0	0	
风扇 Fan	X	0	0	0	0	0	
电源供应器 Power supply	Х	0	0	0	0	0	
电源线 Power Cord	X	0	0	0	0	0	
突波吸收器 TVS Array	X	0	0	0	0	0	
極管 Diode	X	0	0	0	0	0	
电压转换集成电路 Regulator	X	0	0	0	0	0	
保险丝 FUSE	X	0	0	0	0	0	
无线连接器 RF CONN	Х	0	0	0	0	0	
螺丝帽 NUT	Х	0	0	0	0	0	
电阻 Resistor	X	0	0	0	0	0	

|本表格依据 SJ/T:11364-2014 的规定编制。

X:表示此部件使用的至少一种同类材料中,此种有毒或有害物质的含量高于 GB/T 26572-2011 规定的限制要求。

X: indicates the toxic or hazardous substance content of the part (at the homogenous material level) is over the threshold defined by standard of GB/T 26572-2011("Contained"toxic or hazardous substances). Suppliers can explain the technical cause of "X" according to actual situation.

〇:表示此部件使用的所有同类材料中此种有毒或有害物质的含量均低于 GB/T 26572-2011 规定的限制要求

indicates the toxic or hazardous substance content of the part (at the homogenous material level) is lower than the threshold defined by Requirements for Concentration Limits for Toxic or hazardous Substances in Electronic Information Products(GB/T 26572-2011) issued by Chinese Ministry of Information Industry ("Not Contained" toxic or hazardous substances).

The following tables are a declaration of the presence condition of restricted substances:

設備名稱:Ethe	ernet Switch		型號(型式):	AS9726-32DB				
Equipment nam	е	-	Type designatio					
		限用物質及其化學符號 Restricted substances and its chemical symbols						
單元Unit	鉛Lead (Pb)	汞Mercury (Hg)	鎘Cadmium (Cd)	六價鉻 Hexavalent chromium (Cr+6)	多溴聯苯 Polybrominate d biphenyls (PBB)	多溴二苯醚 Polybrominate d diphenyl ethers (PBDE)		
電路板組件 PCBA	발	0	0	0	0	0		
風扇 Fan	1270 41	0	0	0	0	0		
散熱器 Heatsink	0	0	0	0	0	0		
機殼 Chassis	•	0	0	0	0	0		
線材 Cable Assy	0	0	0	0	0	0		
電源線 Power Cord	~	0	0	0	0	0		
電源供應器 Power Supply	F2%	0	0	0	0	0		

備考1. ^{*}超出0.1 wt % ^{*} 及 ^{*}超出0.01 wt % ^{*} 係指限用物質之百分比含量超出百分比含量基準值。 Note 1:"Exceeding 0.1 wt %" and "exceeding 0.01 wt %" indicate that the percentage content of the restricted substance exceeds the reference percentage value of presence condition.

備考2. "○" 係指該項限用物質之百分比含量未超出百分比含量基準值。

Note 2: " \bigcirc " indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence.

備考3. "-"係指該項限用物質為排除項目。

Note 3: The "-" indicates that the restricted substance corresponds to the exemption.

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Signature:

Date: